

DRV134
DRV135

AUDIO BALANCED LINE DRIVERS

FEATURES

- BALANCED OUTPUT
- LOW DISTORTION: 0.0005% at $f = 1\text{kHz}$
- WIDE OUTPUT SWING: 17V_{rms} into 600 Ω
- HIGH CAPACITIVE LOAD DRIVE
- HIGH SLEW RATE: 15V/ μs
- WIDE SUPPLY RANGE: $\pm 4.5\text{V}$ to $\pm 18\text{V}$
- LOW QUIESCENT CURRENT: $\pm 5.2\text{mA}$
- 8-PIN DIP, SO-8, AND SOL-16 PACKAGES
- COMPANION TO AUDIO DIFFERENTIAL LINE RECEIVERS: INA134 and INA137
- IMPROVED REPLACEMENT FOR SSM2142

APPLICATIONS

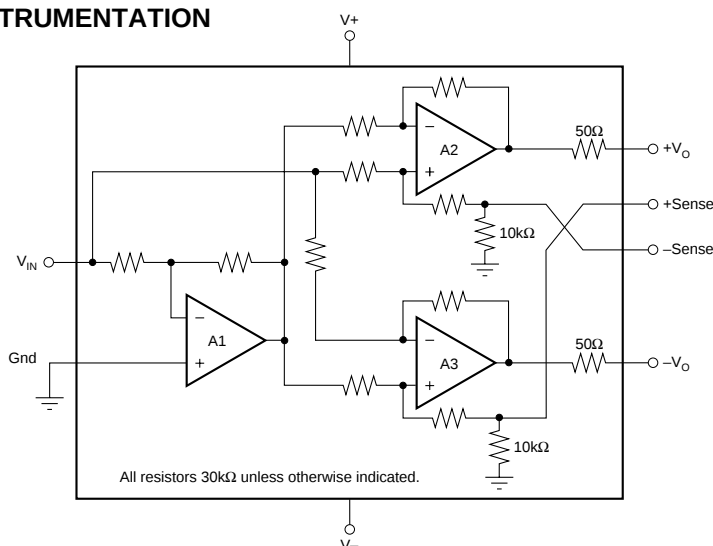
- AUDIO DIFFERENTIAL LINE DRIVER
- AUDIO MIX CONSOLES
- DISTRIBUTION AMPLIFIER
- GRAPHIC/PARAMETRIC EQUALIZERS
- DYNAMIC RANGE PROCESSORS
- DIGITAL EFFECTS PROCESSORS
- TELECOM SYSTEMS
- HI-FI EQUIPMENT
- INDUSTRIAL INSTRUMENTATION

DESCRIPTION

The DRV134 and DRV135 are differential output amplifiers that convert a single-ended input to a balanced output pair. These balanced audio drivers consist of high performance op amps with on-chip precision resistors. They are fully specified for high performance audio applications and have excellent ac specifications, including low distortion (0.0005% at 1kHz) and high slew rate (15V/ μs).

The on-chip resistors are laser-trimmed for accurate gain and optimum output common-mode rejection. Wide output voltage swing and high output drive capability allow use in a wide variety of demanding applications. They easily drive the large capacitive loads associated with long audio cables. Used in combination with the INA134 or INA137 differential receivers, they offer a complete solution for transmitting analog audio signals without degradation.

The DRV134 is available in 8-pin DIP and SOL-16 surface-mount packages. The DRV135 comes in a space-saving SO-8 surface-mount package. Both are specified for operation over the extended industrial temperature range, -40°C to $+85^{\circ}\text{C}$ and operate from -55°C to $+125^{\circ}\text{C}$.



SPECIFICATIONS: $V_S = \pm 18V$

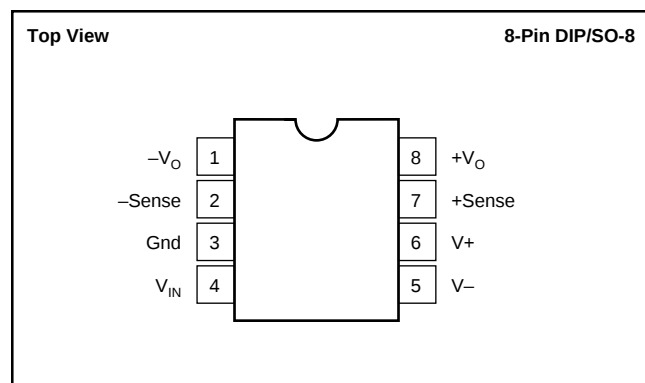
At $T_A = +25^\circ C$, $V_S = \pm 18V$, $R_L = 600\Omega$ differential connected between $+V_O$ and $-V_O$, unless otherwise noted.

PARAMETER		CONDITIONS	DRV134PA, UA DRV135UA			UNITS
			MIN	TYP	MAX	
AUDIO PERFORMANCE						
Total Harmonic Distortion + Noise	THD+N	f = 20Hz to 20kHz,V _O = 10Vrms		0.001		%
		f = 1kHz, V _O = 10Vrms		0.0005		%
Noise Floor, RTO ⁽¹⁾		20kHz BW		−98		dBu
Headroom, RTO ⁽¹⁾		THD+N < 1%		+27		dBu
INPUT						
Input Impedance ⁽²⁾	Z _{IN}			10		kΩ
Input Current	I _{IN}	V _{IN} = ±7.07V		±700	±1000	μA
GAIN						
Differential		[(+V _O) − (−V _O)]/V _{IN}				
Initial		V _{IN} = ±10V	5.8	6		dB
Error				±0.1	±2	%
vs Temperature				±10		ppm/°C
Single-Ended		V _{IN} = ±5V				
Initial			5.8	6		dB
Error				±0.7	±2	%
vs Temperature				±10		ppm/°C
Nonlinearity				0.0003		% of FS
OUTPUT						
Common-Mode Rejection, f = 1kHz	OCMR	See OCMR Test Circuit, Figure 4	46	68		dB
Signal Balance Ratio, f = 1kHz	SBR	See SBR Test Circuit, Figure 5	35	54		dB
Output Offset Voltage						
Offset Voltage, Common-Mode	V _{OCM} ⁽³⁾	V _{IN} = 0		±50	±250	mV
vs Temperature				±150		μV/°C
Offset Voltage, Differential	V _{OD} ⁽⁴⁾	V _{IN} = 0		±1	±10	mV
vs Temperature				±5		μV/°C
vs Power Supply	PSRR	V _S = ±4.5V to ±18V	80	110		dB
Output Voltage Swing, Positive		No Load ⁽⁵⁾	(V+) − 3	(V+) − 2.5		V
Negative		No Load ⁽⁵⁾	(V−) + 2	(V−) + 1.5		V
Impedance				50		Ω
Load Capacitance, Stable Operation	C _L	C _L Tied to Ground (each output)		1		μF
Short-Circuit Current	I _{SC}			±85		mA
FREQUENCY RESPONSE						
Small-Signal Bandwidth				1.5		MHz
Slew Rate	SR			15		V/μs
Settling Time: 0.01%		V _{OUT} = 10V Step		2.5		μs
Overload Recovery		Output Overdriven 10%		3		μs
POWER SUPPLY						
Rated Voltage	V _S			±18		V
Voltage Range			±4.5		±18	V
Quiescent Current	I _Q	I _O = 0		±5.2	±5.5	mA
TEMPERATURE RANGE						
Specification Range			−40		+85	°C
Operation Range			−55		+125	°C
Storage Range			−55		+125	°C
Thermal Resistance	θ _{JA}					
8-Pin DIP				100		°C/W
SO-8 Surface Mount				150		°C/W
SOL-16 Surface Mount				80		°C/W

NOTES: (1) dBu = $20\log(V_{rms}/0.7746)$. (2) Resistors are ratio matched but have $\pm 20\%$ absolute value. (3) $V_{OCM} = [(+V_O) + (-V_O)]/2$. (4) $V_{OD} = (+V_O) - (-V_O)$. (5) Guarantees linear operation. Includes common-mode offset.

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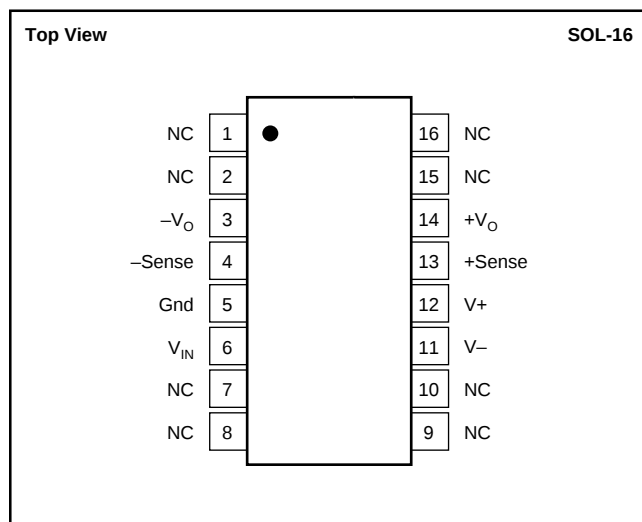
PIN CONFIGURATIONS



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V_+ to V_-	40V
Input Voltage Range	V_- to V_+
Output Short-Circuit (to ground)	Continuous
Operating Temperature	-55°C to $+125^{\circ}\text{C}$
Storage Temperature	-55°C to $+125^{\circ}\text{C}$
Junction Temperature	$+150^{\circ}\text{C}$
Lead Temperature (soldering, 10s)	$+300^{\circ}\text{C}$

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may affect device reliability.



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

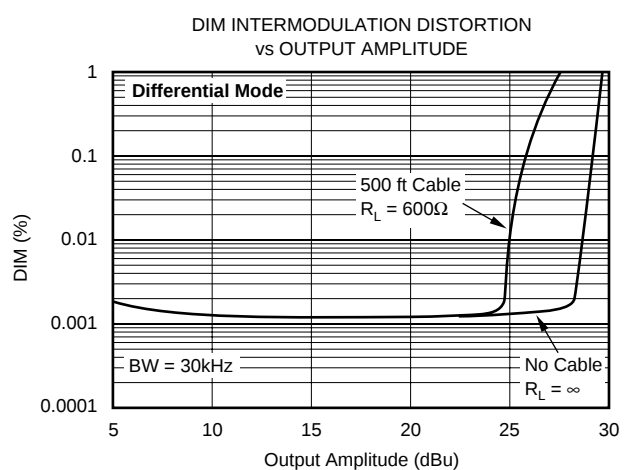
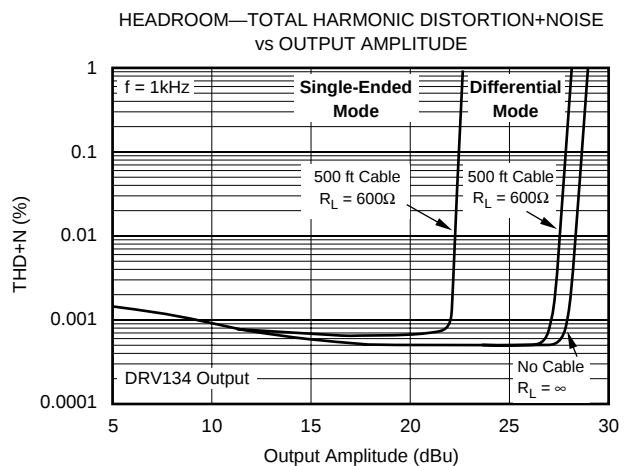
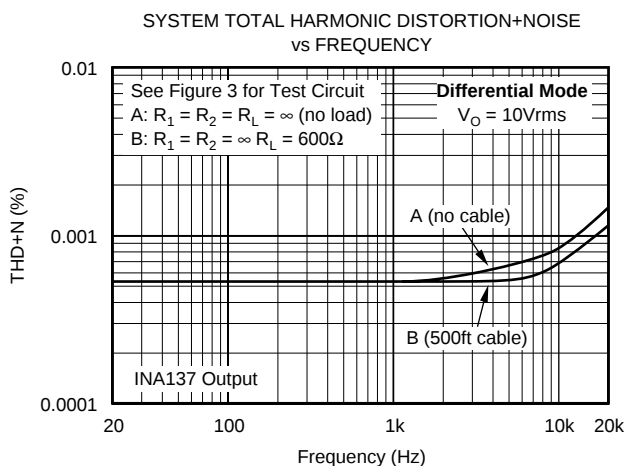
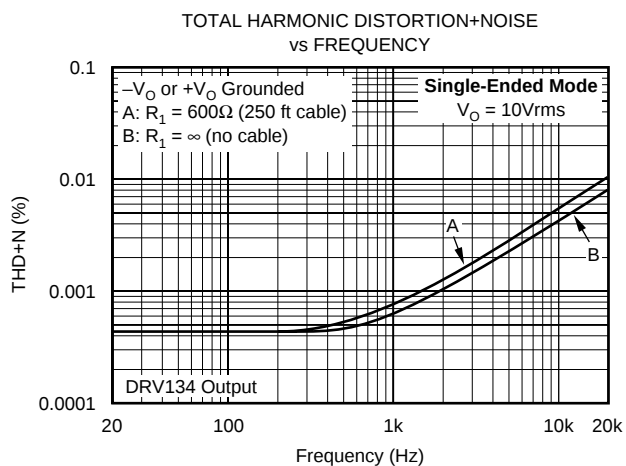
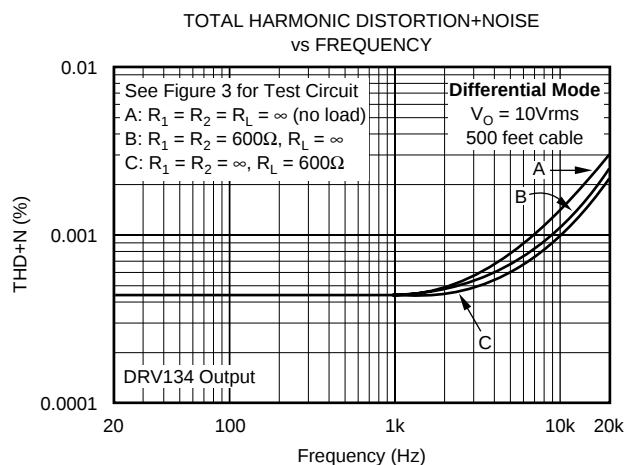
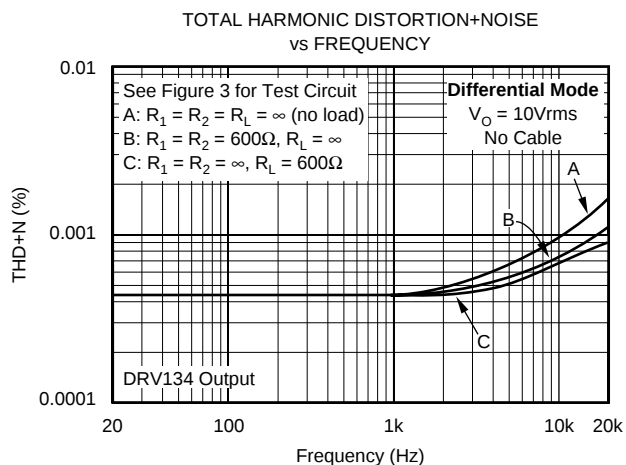
PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER ⁽²⁾	TRANSPORT MEDIA
DRV134PA	8-Pin DIP	006	-40°C to $+85^{\circ}\text{C}$	DRV134PA	Rails
DRV134UA	SOL-16 Surface Mount	211	-40°C to $+85^{\circ}\text{C}$	DRV134UA	Rails
"	"	"	"	DRV134UA/1K	Tape and Reel
DRV135UA	SO-8 Surface Mount	182	-40°C to $+85^{\circ}\text{C}$	DRV135UA	Rails
"	"	"	"	DRV135UA/2K5	Tape and Reel

NOTES: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book. For detailed Tape and Reel mechanical information refer to Appendix B of Burr-Brown IC Data Book. (2) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 2500 pieces of "DRV135UA/2K5" will get a single 2500-piece Tape and Reel. For detailed Tape and Reel mechanical information, refer to Appendix B of Burr-Brown IC Data Book.

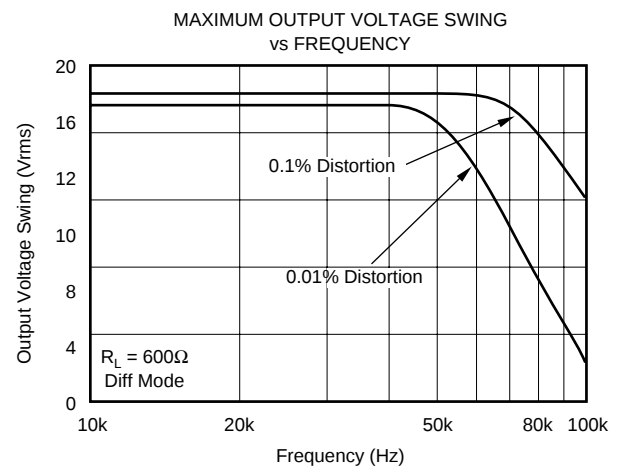
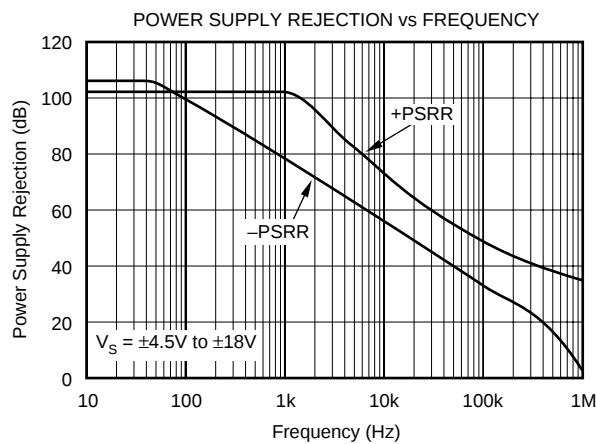
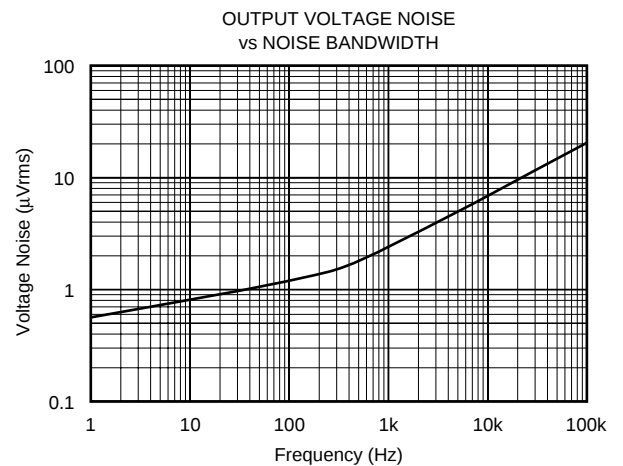
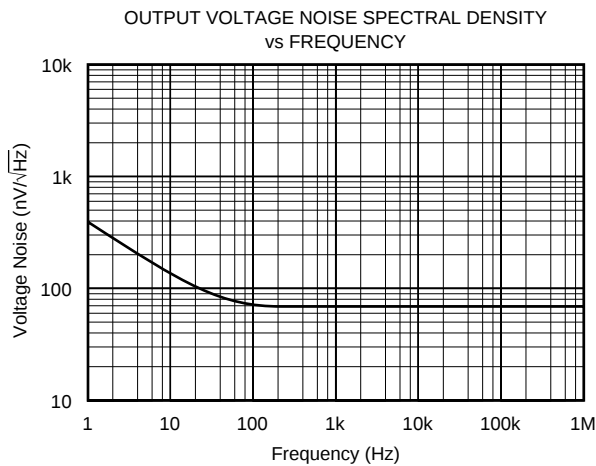
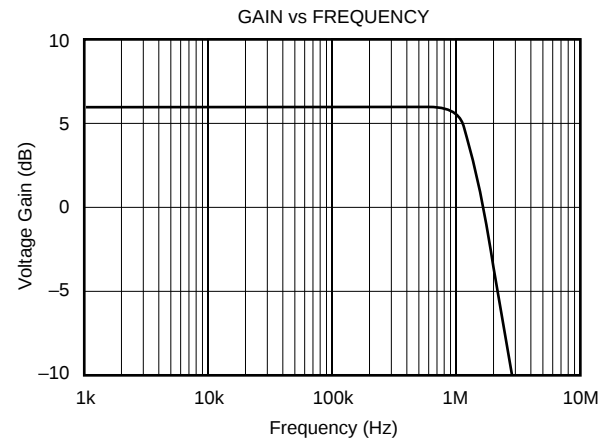
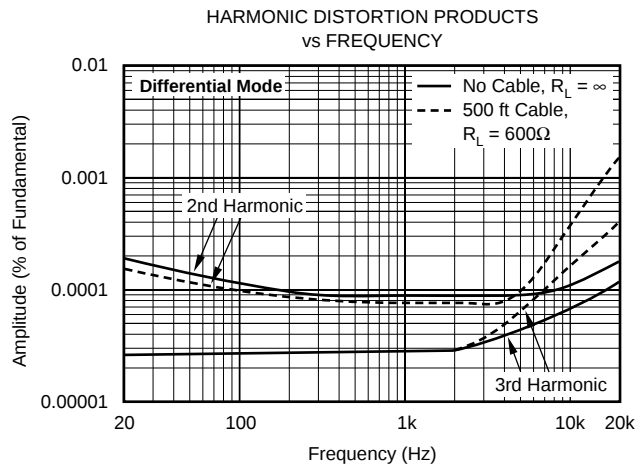
TYPICAL PERFORMANCE CURVES

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, $R_L = 600\Omega$ differential connected between $+V_O$ and $-V_O$, unless otherwise noted.



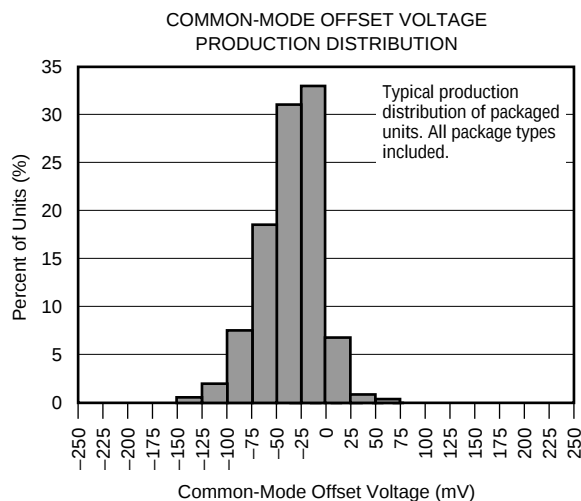
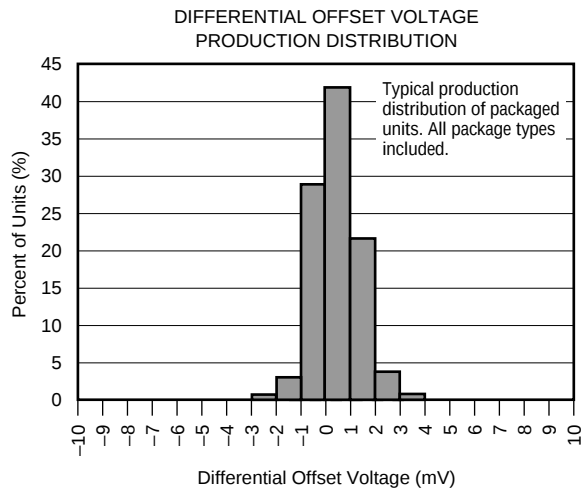
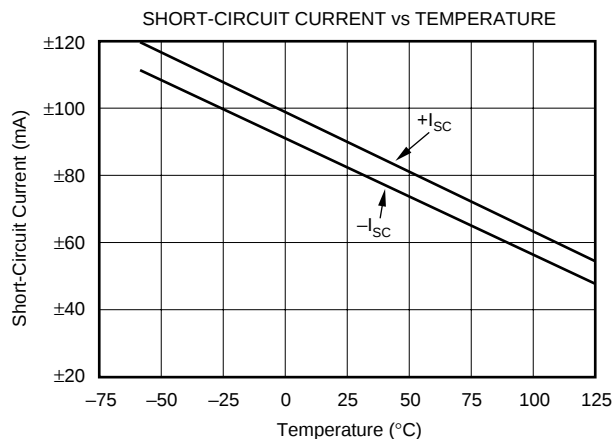
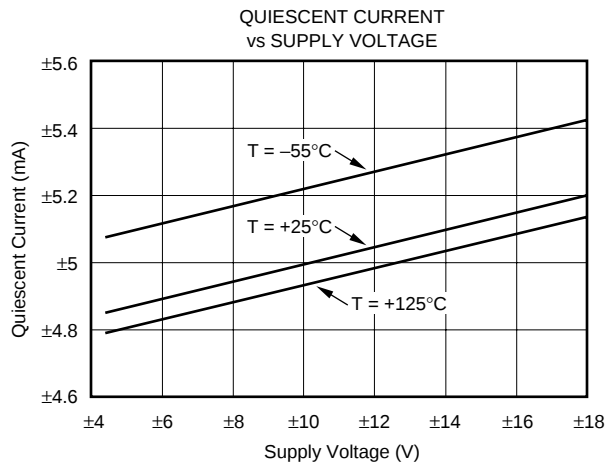
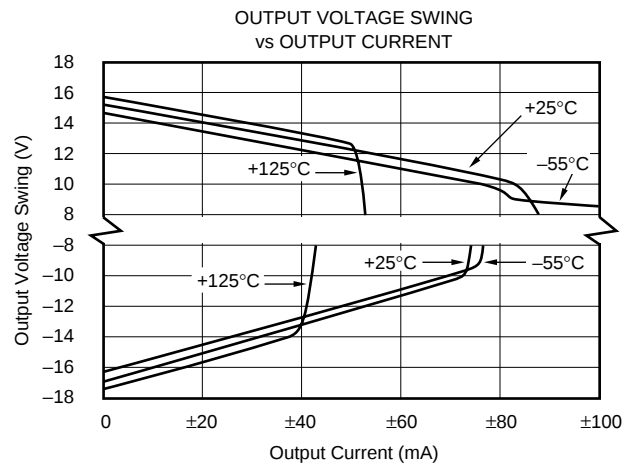
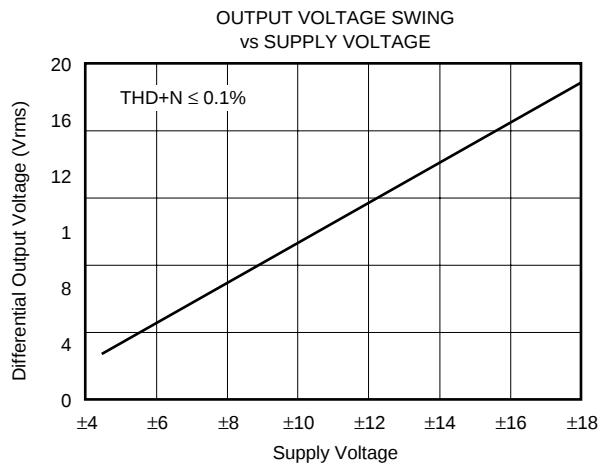
TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, $R_L = 600\Omega$ differential connected between $+V_O$ and $-V_O$, unless otherwise noted.



TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, $R_L = 600\Omega$ differential connected between $+V_O$ and $-V_O$, unless otherwise noted.

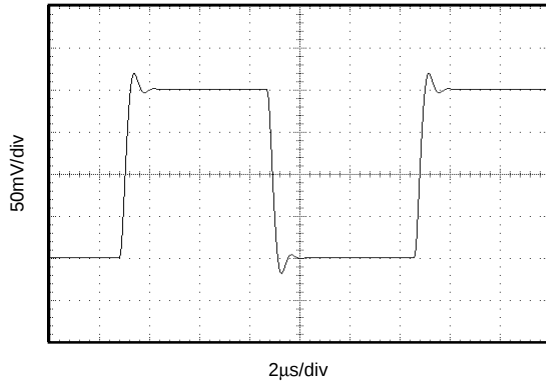


TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, $R_L = 600\Omega$ differential connected between $+V_O$ and $-V_O$, unless otherwise noted.

SMALL-SIGNAL STEP RESPONSE

$C_L = 100\text{pF}$



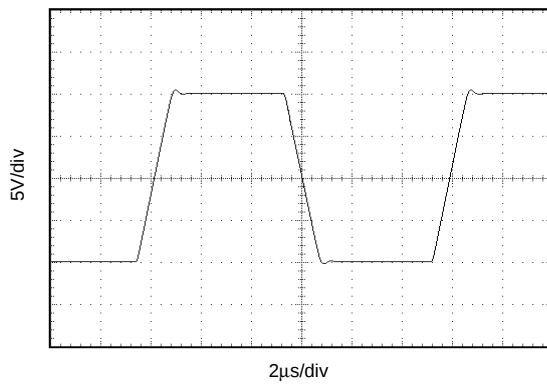
SMALL-SIGNAL STEP RESPONSE

$C_L = 1000\text{pF}$



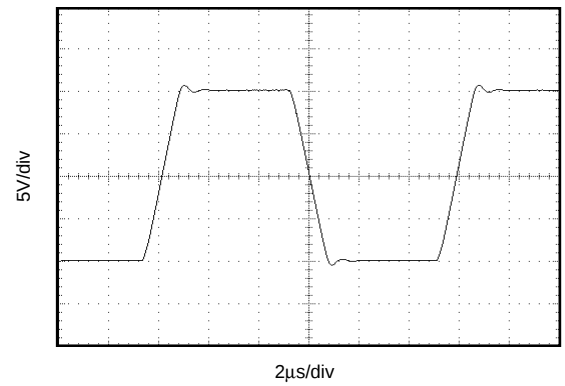
LARGE-SIGNAL STEP RESPONSE

$C_L = 100\text{pF}$

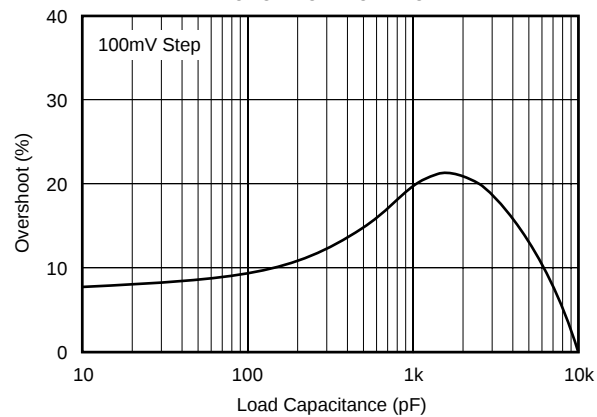


LARGE-SIGNAL STEP RESPONSE

$C_L = 1000\text{pF}$



SMALL-SIGNAL OVERSHOOT
vs LOAD CAPACITANCE



APPLICATIONS INFORMATION

The DRV134 (and DRV135 in SO-8 package) converts a single-ended, ground-referenced input to a floating differential output with +6dB gain ($G = 2$). Figure 1 shows the basic connections required for operation. Decoupling capacitors placed close to the device pins are strongly recommended in applications with noisy or high impedance power supplies.

The DRV134 consists of an input inverter driving a cross-coupled differential output stage with 50Ω series output

resistors. Characterized by low differential-mode output impedance (50Ω) and high common-mode output impedance ($1.6k\Omega$), the DRV134 is ideal for audio applications. Normally, $+V_O$ is connected to +Sense, $-V_O$ is connected to -Sense, and the outputs are taken from these junctions as shown in Figure 1. For applications with large dc cable offset errors, a $10\mu F$ electrolytic nonpolarized blocking capacitor at each sense pin is recommended as shown in Figure 2.

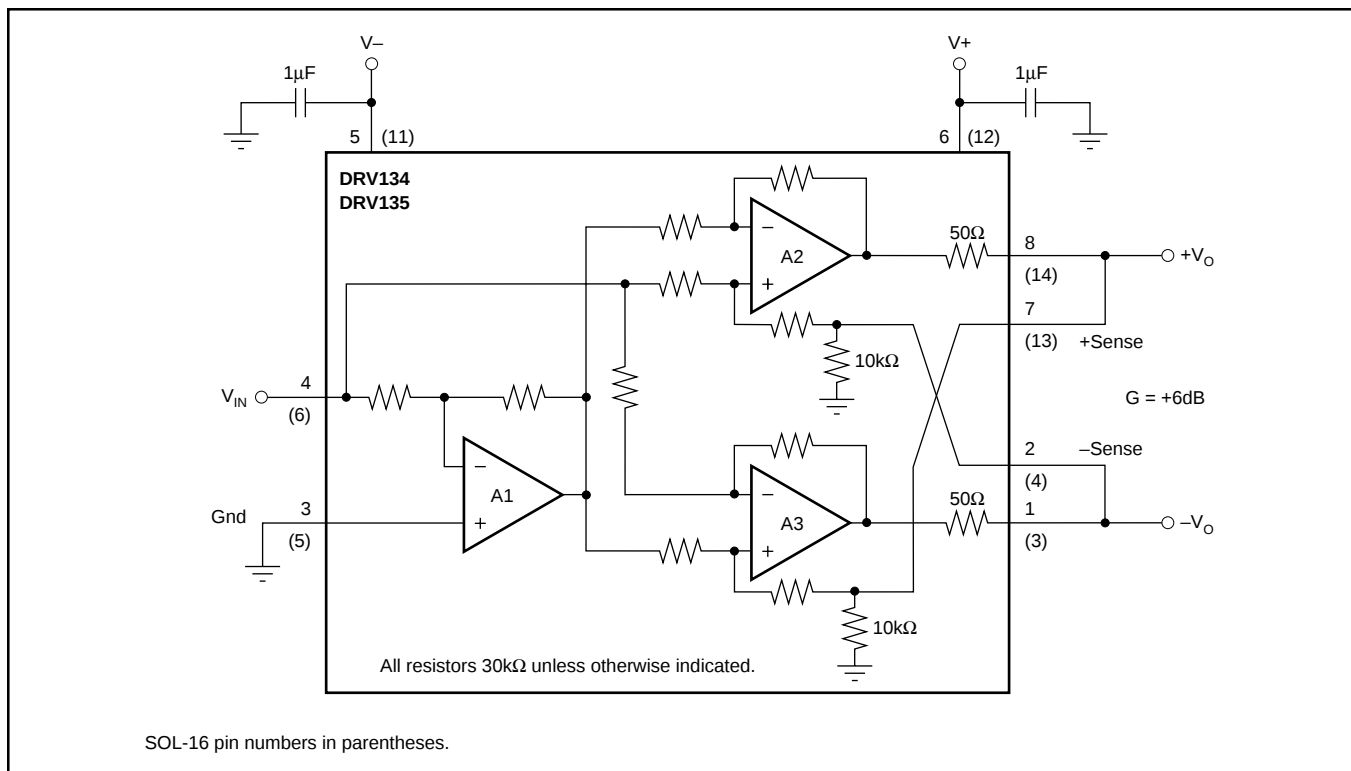


FIGURE 1. Basic Connections.

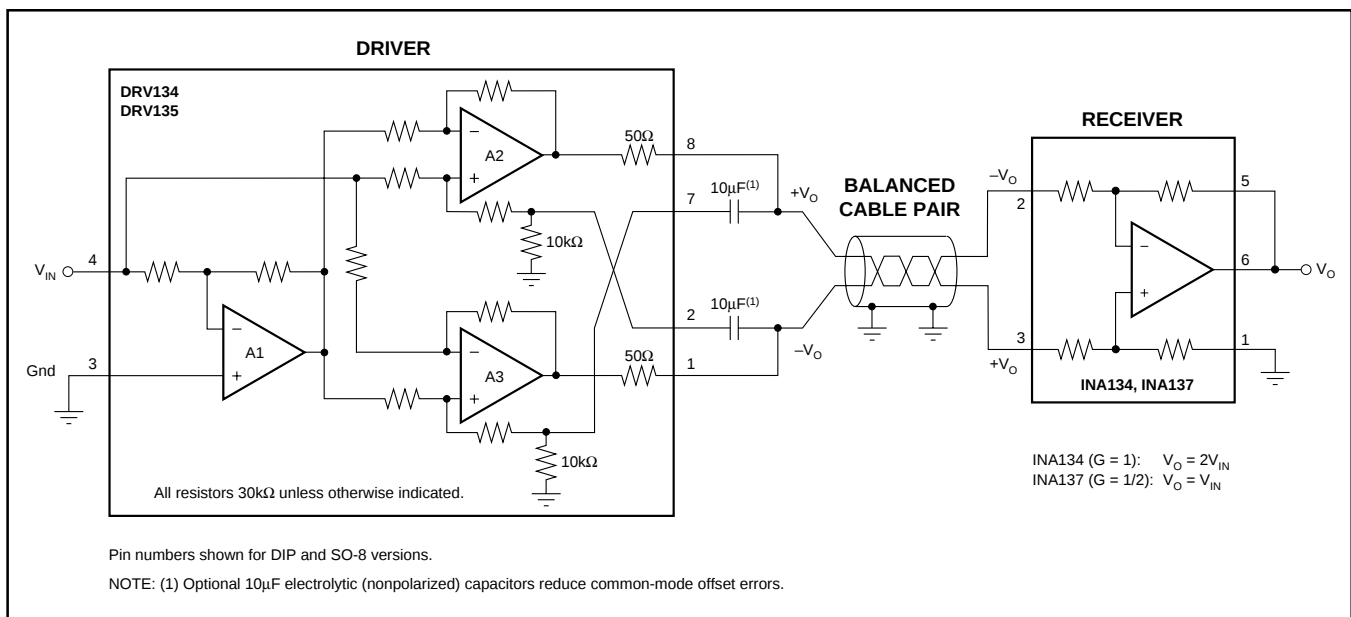


FIGURE 2. Complete Audio Driver/Receiver Circuit.

For best system performance, it is recommended that a high input-impedance difference amplifier be used as the receiver. Used with the INA134 ($G = 0\text{dB}$) or the INA137 ($G = \pm 6\text{dB}$) differential line receivers, the DRV134 forms a complete solution for driving and receiving audio signals, replacing input and output coupling transformers commonly used in professional audio systems (Figure 2). When used with the INA137 ($G = -6\text{dB}$) overall system gain is unity.

The DRV134 was designed for enhanced ac performance. Very low distortion, low noise, and wide bandwidth provide superior performance in high quality audio applications. Laser-trimmed matched resistors provide optimum output common-mode rejection (typically 68dB), especially when compared to circuits implemented with op amps and discrete precision resistors. In addition, high slew rate (15V/ μ s) and fast settling time (2.5 μ s to 0.01%) ensure excellent dynamic response.

The DRV134 has excellent distortion characteristics. As shown in the distortion data provided in the typical performance curves, THD+Noise is below 0.003% throughout the audio frequency range under various output conditions. Both differential and single-ended modes of operation are shown. In addition, the optional 10 μ F blocking capacitors used to minimize V_{OCM} errors have virtually no effect on performance. Measurements were taken with an Audio Precision System One (with the internal 80kHz noise filter) using the THD test circuit shown in Figure 3.

Up to approximately 10kHz, distortion is below the measurement limit of commonly used test equipment. Furthermore, distortion remains relatively constant over the wide output voltage swing range (approximately 2.5V from the positive supply and 1.5V from the negative supply). A special output stage topology yields a design with minimum distortion variation from lot-to-lot and unit-to-unit. Furthermore, the small and large signal transient response curves demonstrate the DRV134's stability under load.

Output common-mode rejection (OCMR) is defined as the change in differential output voltage due to a change in output common-mode voltage. When measuring OCMR, V_{IN} is grounded and a common-mode voltage, V_{CM} , is applied to the output as shown in Figure 4. Ideally no differential mode signal (V_{OD}) should appear. However, a small mode-conversion effect causes an error signal whose magnitude is quantified by OCMR.

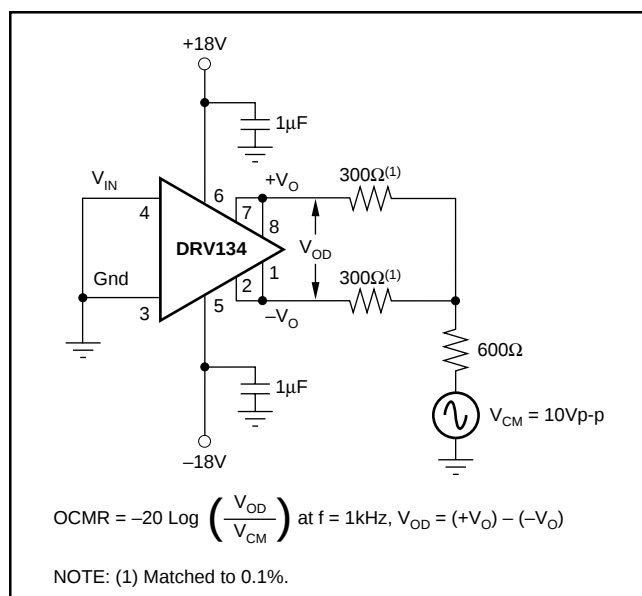


FIGURE 4. Output Common-Mode Rejection Test Circuit.

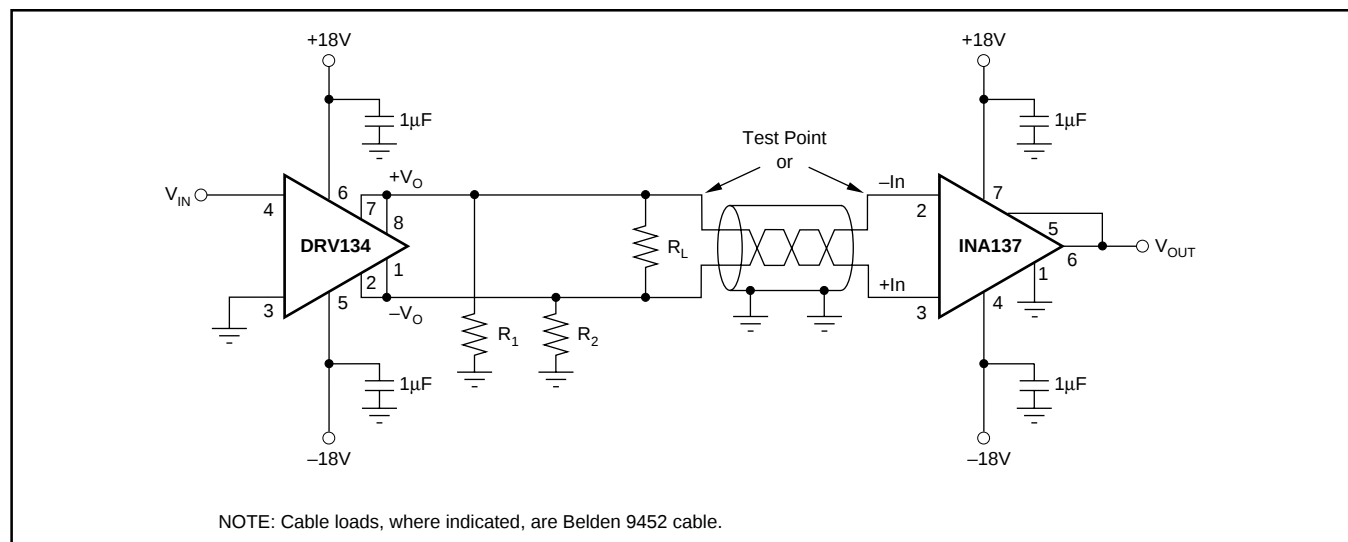


FIGURE 3. Distortion Test Circuit.

SIGNAL BALANCE RATIO

Signal balance ratio (SBR) measures the symmetry of the output signals under loaded conditions. To measure SBR an input signal is applied and the outputs are summed as shown in Figure 5. V_{OUT} should be zero since each output ideally is exactly equal and opposite. However, an error signal results from any imbalance in the outputs. This error is quantified by SBR. The impedances of the DRV134's output stages are closely matched by laser trimming to minimize SBR errors. In an application, SBR also depends on the balance of the load network.

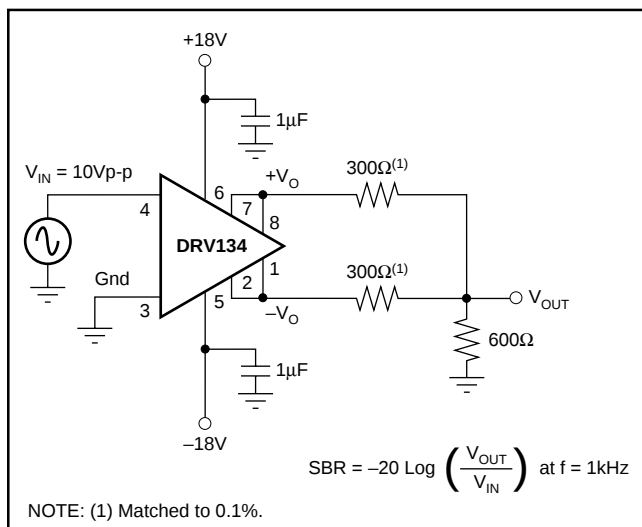


FIGURE 5. Signal Balance Ratio Test Circuit.

SINGLE-ENDED OPERATION

The DRV134 can be operated in single-ended mode without degrading output drive capability. Single-ended operation requires that the unused side of the output pair be grounded (both the V_O and Sense pins) to a low impedance return path. Gain remains +6dB. Grounding the negative outputs as shown in Figure 6 results in a noninverted output signal ($G = +2$) while grounding the positive outputs gives an inverted output signal ($G = -2$).

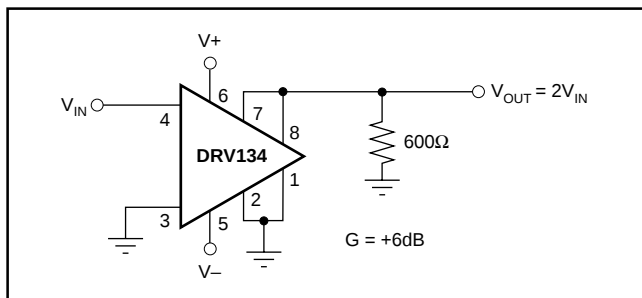


FIGURE 6. Typical Single-Ended Application.

For best rejection of line noise and hum differential mode operation is recommended. However, single-ended performance is adequate for many applications. In general single-ended performance is comparable to differential mode (see THD+N typical performance curves), but the common-mode and noise rejection inherent in balanced-pair systems is lost.

CABLE

The DRV134 is capable of driving large signals into 600Ω loads over long cables. Low impedance shielded audio cables such as the standard Belden 8451 or 9452 (or similar) are recommended, especially in applications where long cable lengths are required.

THERMAL PERFORMANCE

The DRV134 and DRV135 have robust output drive capability and excellent performance over temperature. In most applications there is no significant difference between the DIP, SOL-16, and SO-8 packages. However, for applications with extreme temperature and load conditions, the SOL-16 (DRV134UA) or DIP (DRV134PA) packages are recommended. Under these conditions, such as loads greater than 600Ω or very long cables, performance may be degraded in the SO-8 (DRV135UA) package.

LAYOUT CONSIDERATIONS

A driver/receiver balanced-pair (such as the DRV134 and INA137) rejects the voltage differences between the grounds at each end of the cable, which can be caused by ground currents, supply variations, etc. In addition to proper bypassing, the suggestions below should be followed to achieve optimal OCMR and noise rejection.

- The DRV134 input should be driven by a low impedance source such as an op amp or buffer.
- As is the case for any single-ended system, the source's common should be connected as close as possible to the DRV134's ground. Any ground offset errors in the source will degrade system performance.
- Symmetry on the outputs should be maintained.
- Shielded twisted-pair cable is recommended for all applications. Physical balance in signal wiring should be maintained. Capacitive differences due to varying wire lengths may result in unequal noise pickup between the pair and degrade OCMR. Follow industry practices for proper system grounding of the cables.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
DRV134PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
DRV134PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
DRV134UA	ACTIVE	SOIC	DW	16	48	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DRV134UA/1K	ACTIVE	SOIC	DW	16	1000	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DRV134UA/1KE4	ACTIVE	SOIC	DW	16	1000	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DRV134UAE4	ACTIVE	SOIC	DW	16	48	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DRV135UA	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DRV135UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DRV135UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DRV135UAG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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